

IN THE SPECIFICATION:

Please amend the specification as follows.

On page 1, please replace paragraph [0001] with the following paragraph (showing the marked-up changes):

--Figure 1 is a schematic side-view of a prior art package assembly for a semiconductor device. In this configuration, which is known as a “flip-chip” package, the active device, here shown as semiconductor die 11, is inverted so that the active side of the die is facing ~~away from~~ the package substrate 13. An advantage of this configuration is that it facilitates heat dissipation from the back of the semiconductor die 11 directly to a heat removal device such as a heat sink.--